

# LNPTM THERMOTUFTM COMPOUND WF008N

## **DESCRIPTION**

LNP THERMOTUF WF008N compound is based on Polybutylene Terephthalate (PBT) resin containing 40% glass fiber. Added features of this grade include: Impact Modified, Good Metal Bonding Strength and Good Chemical Resistance targeted for Nano-Molding Technology (NMT) applications.

GENERAL INFORMATION	
Features	Chemical Resistance, Nano molding technology, High stiffness/Strength, Impact resistant, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polybutylene Terephthalate (PBT)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

## **TYPICAL PROPERTY VALUES**

PROPERTIES TYPICAL VALUES UNITS **TEST METHODS** MECHANICAL<sup>(1)</sup> MPa Tensile Stress, brk, Type I, 5 mm/min 133 ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 2.4 % ASTM D638 Tensile Modulus, 5 mm/min 11600 ASTM D638 MPa Flexural Stress, brk, 1.3 mm/min, 50 mm span 205 MPa ASTM D790 Flexural Modulus, 1.3 mm/min, 50 mm span 11000 MPa ASTM D790 Tensile Stress, break, 5 mm/min 134 MPa ISO 527 Tensile Strain, break, 5 mm/min 2.5 % ISO 527 Tensile Modulus, 1 mm/min 11700 MPa ISO 527 Flexural Stress, break, 2 mm/min 217 MPa ISO 178 ISO 178 Flexural Modulus, 2 mm/min 11200 MPa Bonding Strength ("T" treatment, shear type) 34 MPa ISO 19095 IMPACT (1) ASTM D4812 Izod Impact, unnotched, 23°C 960 J/m Izod Impact, notched, 23°C 145 J/m ASTM D256 Izod Impact, notched, -30°C 106 J/m ASTM D256 Izod Impact, unnotched 80\*10\*4 +23°C 59 ISO 180/1U kJ/m² Izod Impact, notched 80\*10\*4 +23°C 14 kJ/m² ISO 180/1A Izod Impact, notched 80\*10\*4 -30°C 11 kJ/m² ISO 180/1A THERMAL (1) HDT, 1.82 MPa, 3.2mm, unannealed 193 °C ASTM D648 HDT, 0.45 MPa, 3.2 mm, unannealed °C 217 ASTM D648

© 2024 Copyright by SABIC. All rights reserved

## CHEMISTRY THAT MATTERS

Revision 20241021



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	196	°C	ISO 75/Af
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	218	°C	ISO 75/Bf
CTE, -40°C to 40°C, flow	1.9E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	8.7E-05	1/°C	ASTM E831
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ASTM E831
CTE, 23°C to 50°C, xflow	9.0E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, flow	1.8E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.6E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, flow	1.7E-05	1/°C	ISO 11359-2
CTE, 23°C to 50°C, xflow	8.9E-05	1/°C	ISO 11359-2
Relative Temp Index, Elec <sup>(2)</sup>	75	°C	UL 746B
Relative Temp Index, Mech w/impact <sup>(2)</sup>	75	°C	UL 746B
Relative Temp Index, Mech w/o impact <sup>(2)</sup>	75	°C	UL 746B
PHYSICAL <sup>(1)</sup>			
Density	1.58	g/cm <sup>3</sup>	ISO 1183
Melt Flow Rate, 250°C/5.0 kgf	10	g/10 min	ASTM D1238
Melt Flow Rate, 275°C/5 kgf	22	g/10 min	ASTM D1238
Melt Volume Rate, MVR at 250°C/5.0 kg	7	cm <sup>3</sup> /10 min	ISO 1133
Melt Volume Rate, MVR at 275°C/5 kg	15	cm <sup>3</sup> /10 min	ISO 1133
Mold Shrinkage, flow (3)	0.25	%	SABIC method
Mold Shrinkage, xflow <sup>(3)</sup>	0.65	%	SABIC method
ELECTRICAL <sup>(1)</sup>			
Dielectric Constant, 1.1 GHz	3.78	-	SABIC method
Dielectric Constant, 1.9 GHz	3.76	-	SABIC method
Dielectric Constant, 5 GHz	3.73	-	SABIC method
Dielectric Constant, 10 GHz	3.80	-	SABIC method
Dissipation Factor, 1.1 GHz	0.0104	-	SABIC method
Dissipation Factor, 1.9 GHz	0.0096	-	SABIC method
Dissipation Factor, 5 GHz	0.0091	-	SABIC method
Dissipation Factor, 10 GHz	0.0082	-	SABIC method
FLAME CHARACTERISTICS <sup>(2)</sup>			
UL Yellow Card Link	<u>E207780-104061413</u>		
UL Recognized, 94HB Flame Class Rating	≥0.7	mm	UL 94
INJECTION MOLDING <sup>(4)</sup>			
Drying Temperature	100 – 120	°C	
Drying Time	2 – 4	Hrs	
Drying Time (Cumulative)	8	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	250 – 270	°C	
Nozzle Temperature	255 – 275	°C	
Front - Zone 3 Temperature	250 – 270	°C	
Middle - Zone 2 Temperature	250 – 270	°C	
Rear - Zone 1 Temperature	240 – 260	°C	
Hopper Temperature	40-60	°C	
Mold Temperature <sup>(5)</sup>	100 – 160	°C	
iviola remperature	100 - 100	C	

© 2024 Copyright by SABIC. All rights reserved

CHEMISTRY THAT MATTERS



- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.
- (5) Suggest to use narrow mold temperature 140C~160C for NMT application.

### **MORE INFORMATION**

For curve data and CAE cards, please visit and register at https://materialfinder.sabic-specialties.com

#### DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.